

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	11mΩ@10V	30A
	14mΩ@4.5V	

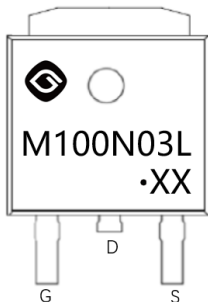
Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

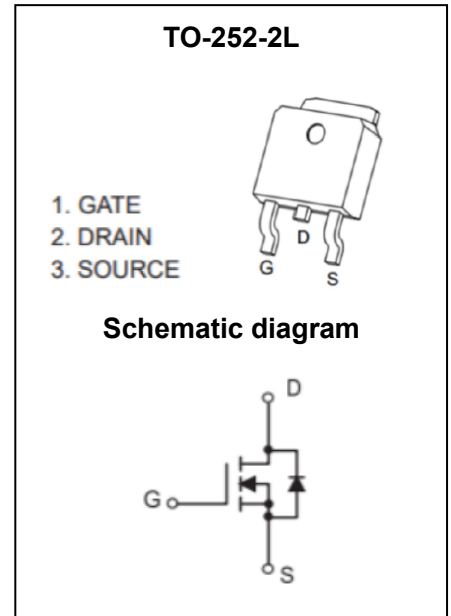
Application

- Power Switching Application

MARKING:



M100N03L = Device Code
 XX = Date Code
 Solid Dot = Green Indicator



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	30	V
Gate - Source Voltage	V_{GS}	±20	V
Continuous Drain Current ¹	I_D	$T_C = 25^\circ\text{C}$	30
		$T_C = 100^\circ\text{C}$	19
Pulsed Drain Current ²	I_{DM}	120	A
Single Pulsed Avalanche Current ³	I_{AS}	12	A
Single Pulsed Avalanche Energy ³	E_{AS}	37	mJ
Power Dissipation ⁵	P_D	25	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	75	$^\circ\text{C/W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	4.9	$^\circ\text{C/W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

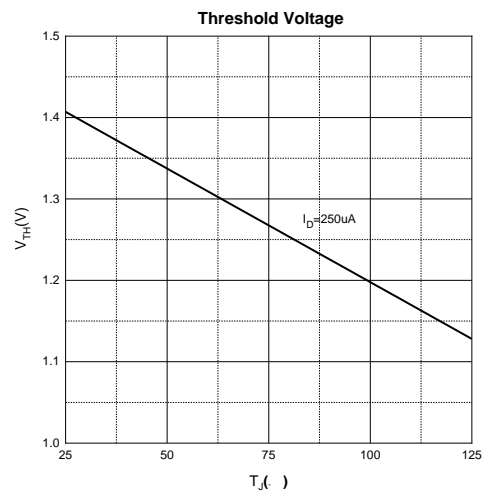
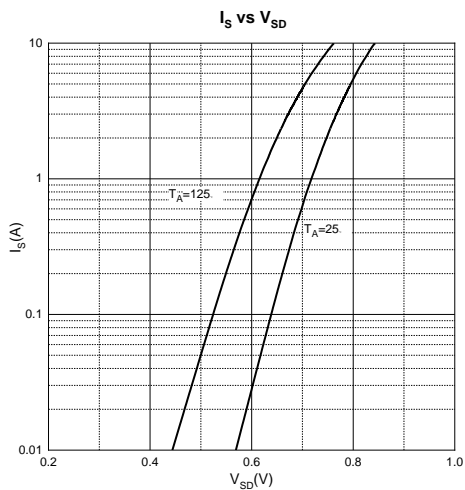
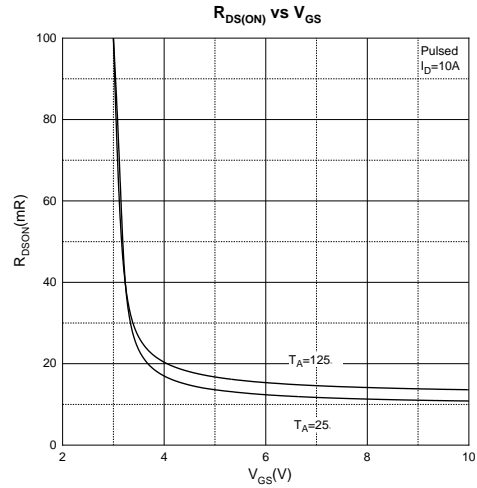
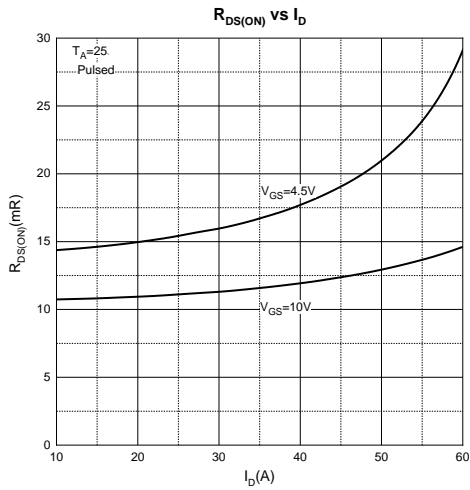
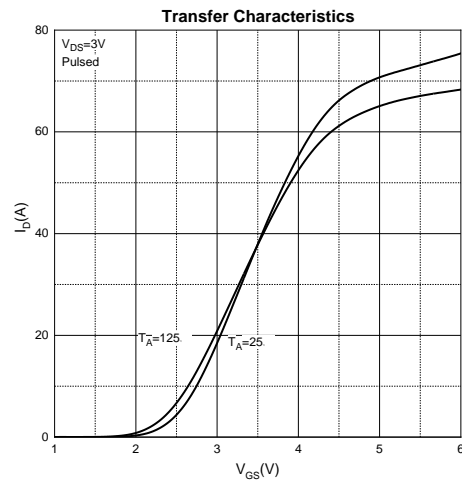
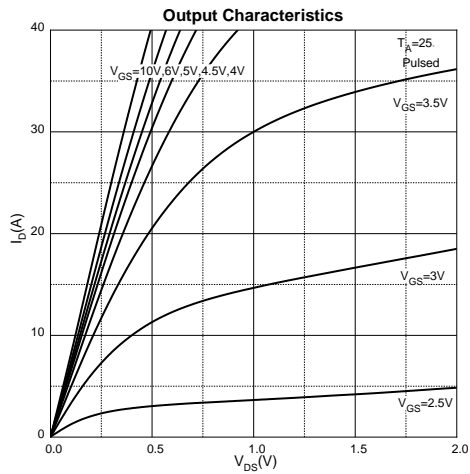
MOSFET ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

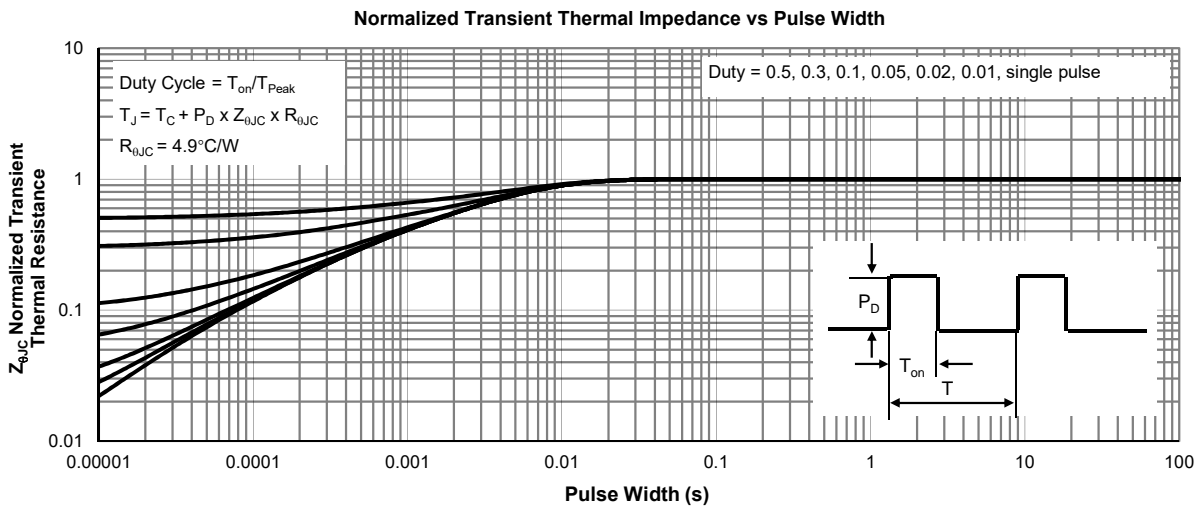
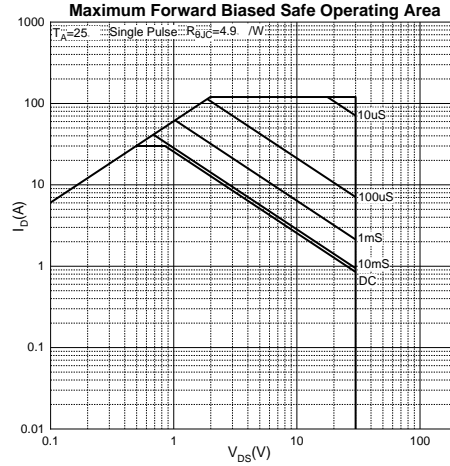
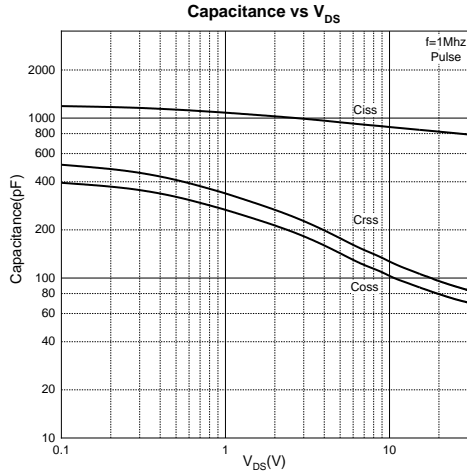
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30V, V_{GS} = 0V$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.4	3.0	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$		11	13	m Ω
		$V_{GS} = 4.5V, I_D = 10A$		14	22	
Forward Transconductance	g_{FS}	$V_{DS} = 10V, I_D = 10A$		16		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 15V, V_{GS} = 0V, f = 1MHz$		847		pF
Output Capacitance	C_{oss}			107		
Reverse Transfer Capacitance	C_{rss}			87		
Gate Resistance	R_g	$V_{DS} = 0V, V_{GS} = 0V$		2.4		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = 25V, V_{GS} = 10V, I_D = 20A$		18.8		nC
Gate-source Charge	Q_{gs}			2.2		
Gate-drain Charge	Q_{gd}			5.4		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15V, V_{GS} = 10V, I_D = 30A$ $R_G = 1.6\Omega$		3		ns
Turn-on Rise Time	t_r			3		
Turn-off Delay Time	$t_{d(off)}$			12		
Turn-off Fall Time	t_f			3		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{GS} = 0V, I_S = 1.7A$			1.2	V

Notes :

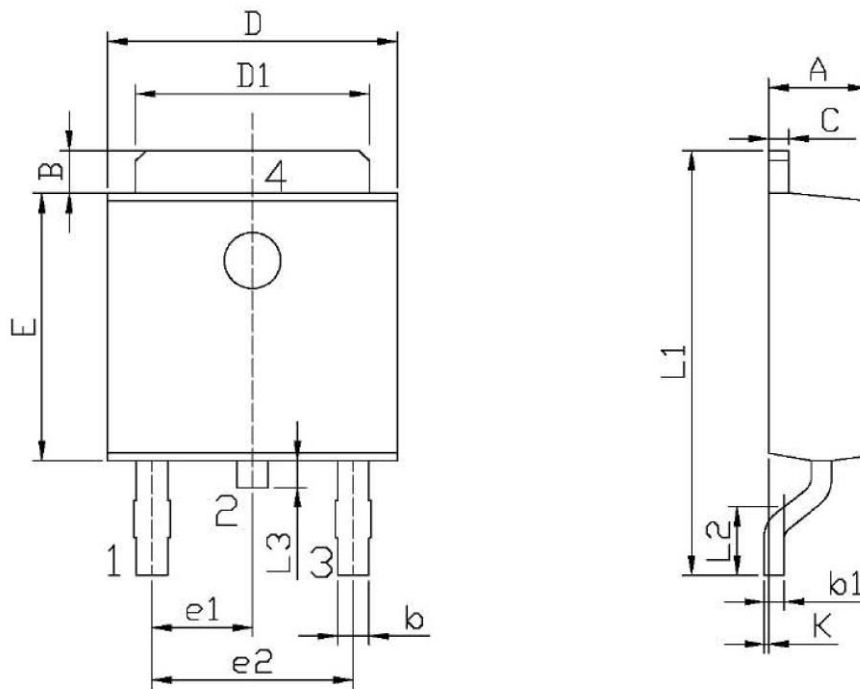
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD} = 15V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics





TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
B	0.950	1.250	0.037	0.049
b	0.500	0.700	0.020	0.028
b1	0.450	0.550	0.018	0.022
C	0.450	0.550	0.018	0.022
D	6.450	6.750	0.254	0.266
D1	5.100	5.500	0.201	0.217
E	5.950	6.250	0.234	0.246
e1	2.240	2.340	0.088	0.092
e2	4.430	4.730	0.174	0.186
L1	9.450	9.950	0.372	0.392
L2	1.250	1.750	0.049	0.069
L3	0.600	0.900	0.024	0.035
K	0.000	0.100	0.000	0.004